

DDR4 DIMM

TE Internal #: 2199154-2 DDR4 DIMM, DIMM Sockets, Double Data Rate (DDR) 4, Board-to-Board, 288 Position, Through Hole - Solder, Vertical Module Orientation

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DRAM Type: Double Data Rate (DDR) 4 Connector System: Board-to-Board Number of Positions: 288 PCB Mounting Style: Through Hole - Solder Module Orientation: Vertical

All DDR4 DIMM SOCKETS (69)

Features

Product Type Features

Center Post

DRAM Type	Double Data Rate (DDR) 4
Connector System	Board-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Product Type	Socket
Configuration Features	
Center Key	Offset Right
Number of Keys	1
Number of Bays	2
Number of Positions	288
Module Orientation	Vertical
Keying	Standard
Number of Rows	2
Electrical Characteristics	
DRAM Voltage	1.2 V

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Body Features

Ejector Material Color	Natural
Retention Post Material	Stainless Steel
Ejector Material	High Temperature Thermoplastic
Ejector Location	Both Ends
Latch Material	High Temperature Thermoplastic
Module Key Type	Offset Right
Latch Color	Black
Retention Post Location	None
Ejector Type	Standard
Contact Features	
Socket Style	DIMM
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	.75 A
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Thickness	.76 μm[30 μin]
Solder Tail Contact Plating Thickness	3 µm[118.1 µin]
Socket Type	Memory Card
ermination Features	
Insertion Style	Direct Insert
Termination Post Length	2.67 mm[.105 in]
lechanical Attachment	
Locating Posts	Without
PCB Mount Retention	With
PCB Mount Retention Type	Boardlock
PCB Mounting Style	Through Hole - Solder
Connector Mounting Type	Board Mount
Boardlock Material	Stainless Steel

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Centerline (Pitch)	.85 mm[.033 in]
Housing Material	High Temperature Nylon
Housing Color	Black
Dimensions	
Center Retention Hole Diameter	1.2 mm[.047 in]
Height Above PC Board	20 mm[.787 in]
Row-to-Row Spacing	2.2 mm[.08 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box & Tray, Tray
Packaging Quantity	80

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Not Yet Reviewed
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2021 (211) Candidate List Declared Against: JUL 2019 (201) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as

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EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series DDR4 DIMM





Customers Also Bought



DDR4 DIMM, DIMM Sockets, Double Data Rate (DDR) 4, Board-to-Board, 288 Position, Through Hole - Solder, Vertical Module Orientation







Documents

Product Drawings DDR4 DIMM 288 Pin TH type

English

DDR4 DIMM 288 Pin TH type

English

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_2199154-2_C4.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2199154-2_C4.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2199154-2_C4.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages DDR4 DIMM Socket Flyer (English)

English

DDR4 DIMM Socket Flyer (Chinese)

Product Specifications

Product Specification

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English